PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Erika SAITO	09/10/2010
Tomoya YAMAURA	09/10/2010
Katsutoshi ITOH	09/13/2010
Masahiko NAITO	09/13/2010
Natsuki ITAYA	09/13/2010
Hideyuki SUZUKI	09/17/2010

RECEIVING PARTY DATA

Name:	SONY CORPORATION	
Street Address:	1-7-1 Konan, Minato-ku,	
City:	Tokyo,	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12939300

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	09812.2148
NAME OF SUBMITTER:	David W. Hill

PATENT REEL: 025313 FRAME: 0812

Total Attachments: 2

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PATENT REEL: 025313 FRAME: 0813

Attorney Docket No. 09812.2148 SONY Ref. No.: S10P1922US00

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

RADIO COMMUNICATION SYSTEM, RADIO COMMUNICATION DEVICE, RADIO COMMUNICATION METHOD, AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto:

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will lestify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in	n this application to insert the serial number and filing date of this application is
the spaces that follow: Serial Number: 12/939,300	
This assignment executed on the dates indicated below.	
ERIKA SAITO	
Name of first or sole inventor TOKYO JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor	
Erika Salto	Saptember 10, 2010
Signature of first or sole inventor	Date of this assignment
TOMOYA YAMAURA	
Name of second inventor	Execution date of U.S. Patent Application
TOKYO JAPAN	···
Residence of second inventor	
Tomova Yamaura	September 10, 2010
Signature of second inventor	Date of this assignment
KATSUTOSHI ITOH	
Name of third inventor	Execution date of U.S. Patent Application
TOKYO JAPAN	
Residence of third inventor	
1 Kul tw	September 13, 20/0.
Signature of third inventor	Date of this assignment

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ADDITIONAL INVENTOR(S)

MASAHIKO NAITO	
Name of fourth inventor TOKYO JAPAN	Execution date of U.S. Patent Application
Residence of fourth inventor Marchile Maile	September 13. 2010
Signature of fourth inventor	Date of this assignment
NATSUKI ITAYA	
Name of fifth inventor TOKYO JAPAN	Execution date of U.S. Patent Application
Residence of fifth inventor Notanki Ctayo	Saptember. 13. 2010
Signature of fifth inventor	Date of this assignment
HIDEYUKI SUZUKI	
Name of sixth inventor TOKYO JAPAN	Execution date of U.S. Patent Application
Residence of sixth inventor	Date of this assignment
Signature of sixth inventor	Date of this assignment
Name of seventh inventor	Execution date of U.S. Patent Application
Residence of seventh inventor	
Signature of seventh inventor	Date of this assignment
Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment
(c.n.	
Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment

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PATENT REEL: 025313 FRAME: 0815